

RD Number: RD115

RD Title: TB62214AFG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C_VCC	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
2	C_VM2	1	0.1μF 50V	—	—	Chip capacitor	3.2mm×1.6mm	
3	CVREFA	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
4	CVREFB	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
5	C_VM1	1	100μF 50V	—	—	Electrolytic capacitor		
6	C_OSCM	1	270pF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
7	CON1	1	Connector	—	—	Connector 4P 2.5		
8	OUT_A-	1	Check terminal	—	—	Logic pin		
9	OUT_A+	1	Check terminal	—	—	Logic pin		
10	OUT_B-	1	Check terminal	—	—	Logic pin		
11	OUT_B+	1	Check terminal	—	—	Logic pin		
12	RSA	1	Check terminal	—	—	Check terminal		
13	RSB	1	Check terminal	—	—	Check terminal		
14	VCC	1	Check terminal	—	—	Check terminal		
15	VDD	1	Check terminal	—	—	Check terminal		
16	VM	1	Check terminal	—	—	Logic pin		
17	VREFA	1	Check terminal	—	—	Check terminal		
18	VREFB	1	Check terminal	—	—	Logic pin		
19	OSCM	1	Check terminal	—	—	Check terminal		
20	INA1	1	Check terminal	—	—	Check terminal		
21	INA2	1	Check terminal	—	—	Check terminal		
22	PHA	1	Check terminal	—	—	Check terminal		
23	PHB	1	Check terminal	—	—	Check terminal		
24	INB1	1	Check terminal	—	—	Check terminal		
25	INB2	1	Check terminal	—	—	Check terminal		

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